



Idaho Department  
of Education

# Public School Facilities Cooperative Funding Program



# Does my LEA qualify?



- Charter schools are **not** eligible
- **Section (2) of 33-909, Idaho Code:**
  - (a) The district has **not** successfully passed at least **one bond or plant facility levy** for repairing, renovating, or replacing unsafe school facilities during the **two years** prior to submitting the application.
  - (b) The administrator of the Division of Occupational and Professional Licenses **has identified unsafe facilities in the district**, and the district has failed to address these issues as required under Chapter 80, Title 39, Idaho Code.
  - (c) The district **has passed** one or more bond or plant facility levies to repair, renovate, or replace unsafe facilities, but the **cost** of fixing the unsafe conditions **exceeds** the amount of money raised by those levies.

# Unsafe Conditions



- Safety deficiency needs to be documented by a qualified person/entity such as DOPL, an engineer, a county building inspector, etc.
- Safety concerns align with the requirements outlined in [Idaho Code Title 39, Chapter 80](#), or IDAPA 24 – Division of Occupational and Professional Licenses, Division of Building Safety – [Uniform School Building Safety, Rule 24.39.60](#).
- In the application, LEA's will explain how the safety deficiency will be mitigated if funds are received.

# Appointed District Supervisor



- If an application approved or modified by the panel **exceeds five million dollars** (\$5,000,000), the Superintendent of Public Instruction must appoint a **district supervisor** within 35 calendar days of plan approval.
- The district supervisor will oversee the project to ensure it is completed as approved and must report regularly to the panel as directed.
- The supervisor will serve for the duration of the project at the pleasure of the Superintendent, with costs for the district supervisor paid by the district.
- [Section 6-2212, Idaho Code](#)

# Project Costs & Requirements



- The panel must consider the most economical solution projected out over 20 years.
  - The panel may modify a proposed project to fit the most economical method to remediate unsafe conditions.
  - If the modified plan is less than the plan that failed in a bond election, it may go out to the electorate for a bond vote.
- Total project costs shall be paid by state Facilities Cooperative Fund.
- District's share of costs is based on the BLEP (Bond Levy Equalization Program) Value Index percentage, if it still existed, in the year the application is submitted.
- All projects must comply with procurement and building code requirements.

# Payback – H292 School District Facilities Fund



With H338, new waterfall of uses for School District Facilities Fund (Section 33-911, changes added in **bold** below):

- a) Payment of any bond passed & issued **prior to July 1, 2025**
- b) Repayment of H338 Facilities Cooperative Fund projects**
- c) Payment of bonds issued after July 1, 2025**
- d) Payment of supplemental school levies
- e) Payment of plant facility levies
- f) New construction, maintenance, renovation, or reserve fund for facilities

# Payback Calculations



- Interest on H338 projects is charged at the end of each fiscal year based on State Idle Fund rate.
- The first year's payment will act as the minimum payment over the 20-year duration.
- Annual payback for H338 projects shall not exceed the annual allocation from the School Facility Fund that is distributed, even if this does not pay the entire district share.
- An LEA must only pay for H338 projects for 20 years, even if this does not reimburse all actual district share costs.
  - This includes years where the H292 distributions result in no payments towards the H338 project due to other bonds being paid.

- **June 12** – Statewide informational webinar for interested school districts
- **June 16** – Application portal opens
  - Panel has 90 days to review and respond to applications
- **July 25** – First round of applications closes
- **August** – Committee reviews first round of applications